

Features

- Trench Power MV MOSFET Technology
- Low Thermal Resistance
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

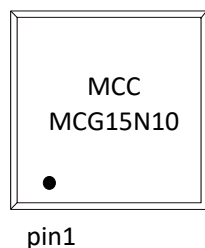
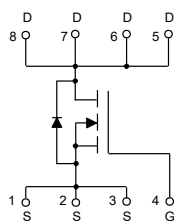
- Operating Junction Temperature Range : -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 60°C/W Junction to Ambient (Note2)
- Thermal Resistance: 4.1°C/W Junction to Case

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	100	V
Gate-Source Voltage	V_{GS}	±20	V
Continuous Drain Current	I_D	15	A
		9.5	
Pulsed Drain Current (Note3)	I_{DM}	60	A
Total Power Dissipation (Note4)	P_D	30.5	W
Single Pulsed Avalanche Energy (Note5)	E_{AS}	20	mJ

Note:

1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-case thermal resistance.
5. $T_J = 25^\circ\text{C}$, $V_{DD} = 50\text{V}$, $V_{GS} = 10\text{V}$, $L = 0.5\text{mH}$.

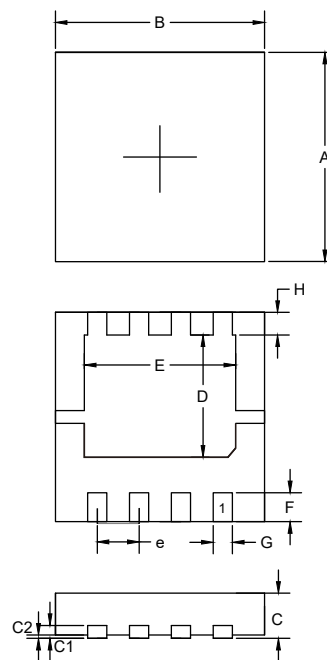
Internal Structure and Marking Code



pin1

N-CHANNEL MOSFET

DFN3333



DIMENSIONS					
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.126	0.130	3.20	3.30	
B	0.126	0.130	3.20	3.30	
C	0.030	0.033	0.75	0.85	
C1	0.007	0.009	0.18	0.22	
C2	---	0.002	---	0.05	
D	0.071	0.079	1.80	2.00	
E	0.087	0.098	2.20	2.50	
F	0.016	0.020	0.40	0.50	
G	0.010	0.014	0.25	0.35	
H	0.012	0.016	0.30	0.40	
e	0.024	0.028	0.60	0.70	

Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	100			V
Gate-Source Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =100V, V _{GS} =0V			1	μA
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	2	3	4	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V, I _D =5A		76	99	mΩ
		V _{GS} =6V, I _D =2.5A		88	120	
Gate Resistance	R _G	f=1MHz, Open drain		0.9		Ω
Diode Characteristics						
Continuous Body Diode Current	I _S				15	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =15A			1.2	V
Reverse Recovery Time	t _{rr}	I _F =7.5A,di/dt=685A/μs		25		ns
Reverse Recovery Charge	Q _{rr}			144		nC
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =50V,V _{GS} =0V,f=1MHz		1273		pF
Output Capacitance	C _{oss}			31		
Reverse Transfer Capacitance	C _{rss}			24		
Total Gate Charge	Q _g	V _{DS} =50V,V _{GS} =10V,I _D =7.5A		20.3		nC
Gate-Source Charge	Q _{gs}			5.4		
Gate-Drain Charge	Q _{gd}			4.8		
Turn-On Delay Time	t _{d(on)}	V _{DD} =50V, V _{GS} =10V, R _G =2.2Ω, I _D =7.5A		10		ns
Turn-On Rise Time	t _r			30		
Turn-Off Delay Time	t _{d(off)}			19.7		
Turn-Off Fall Time	t _f			2.2		

Curve Characteristics

Fig. 1 - Typical Output Characteristics

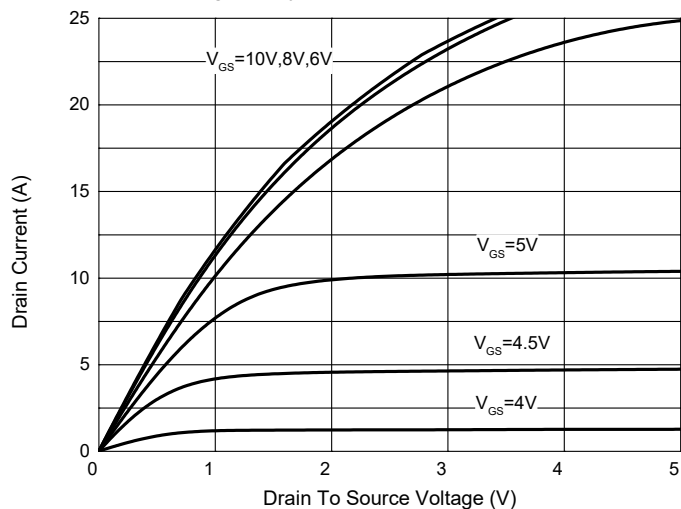


Fig. 2 - Transfer Characteristics

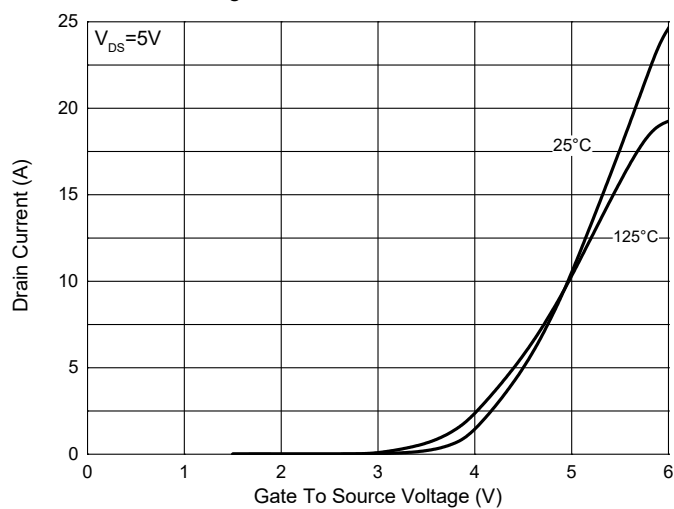


Fig. 3 - $R_{DS(ON)} - V_{GS}$

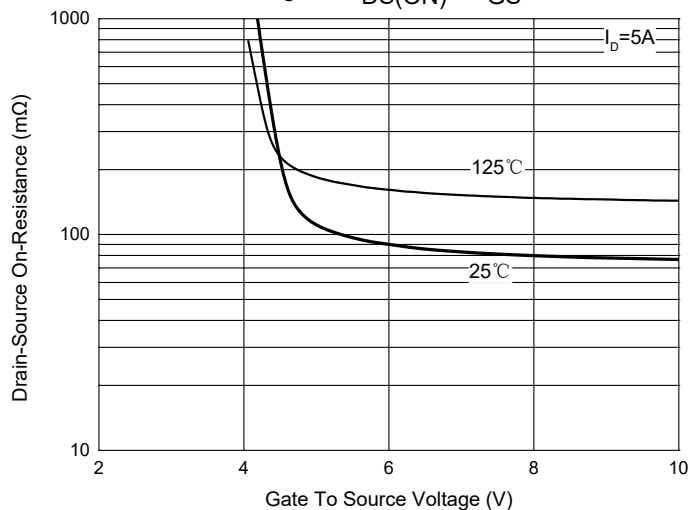


Fig. 4 - $R_{DS(ON)} - I_D$

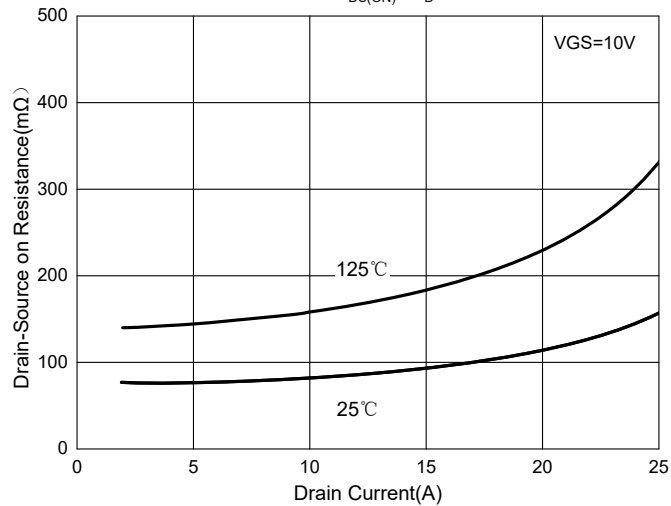


Fig. 5 - Capacitance Characteristics

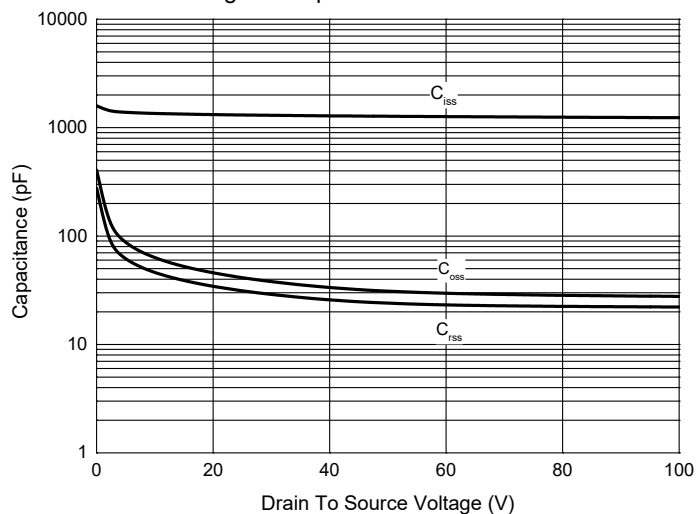
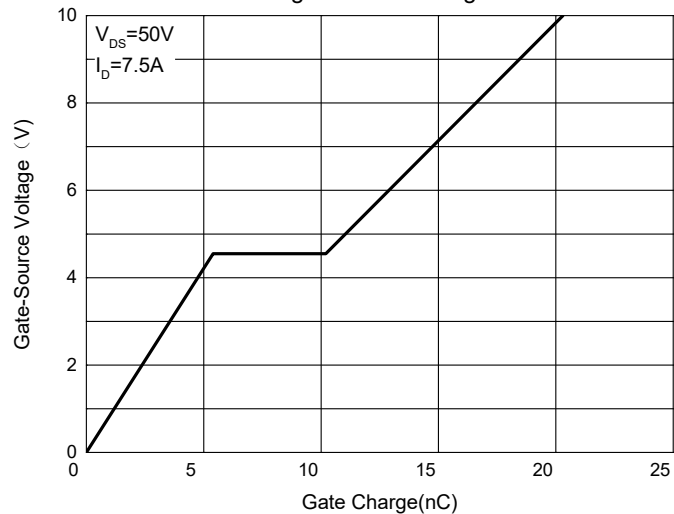


Fig. 6 - Gate Charge



Curve Characteristics

Fig. 7 - Normalized Threshold Voltage

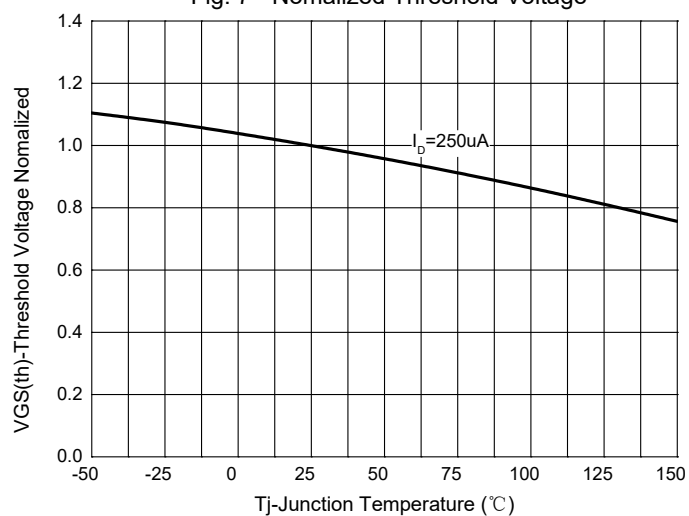


Fig.8-Normalized On Resistance Characteristics

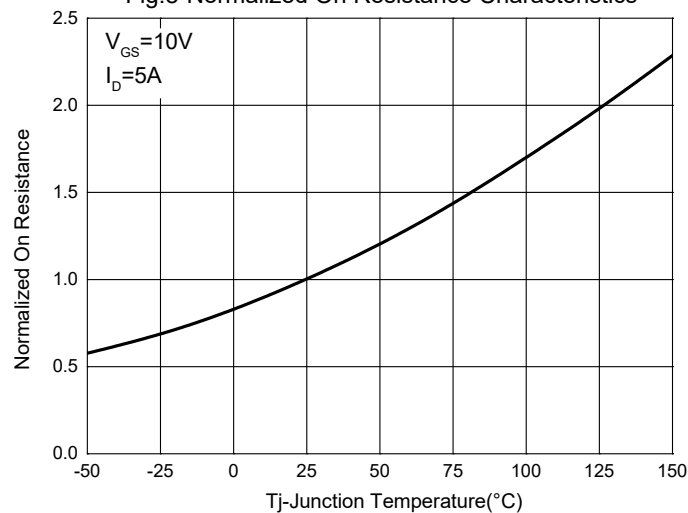


Fig.9 - I_S — V_{SD}

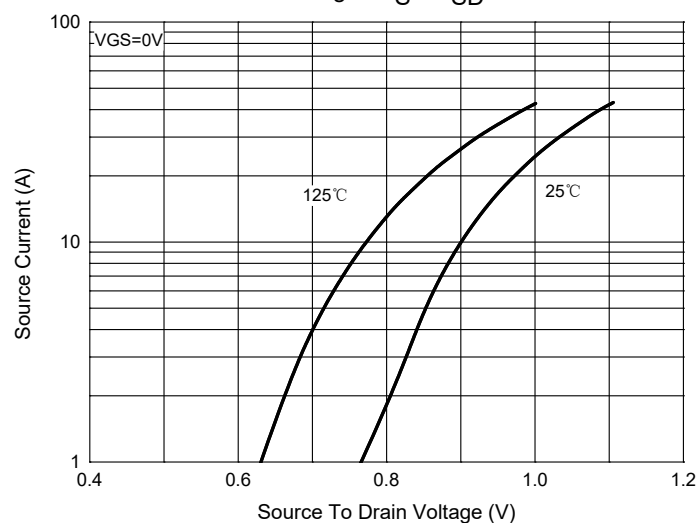


Fig. 10 - Drain Current

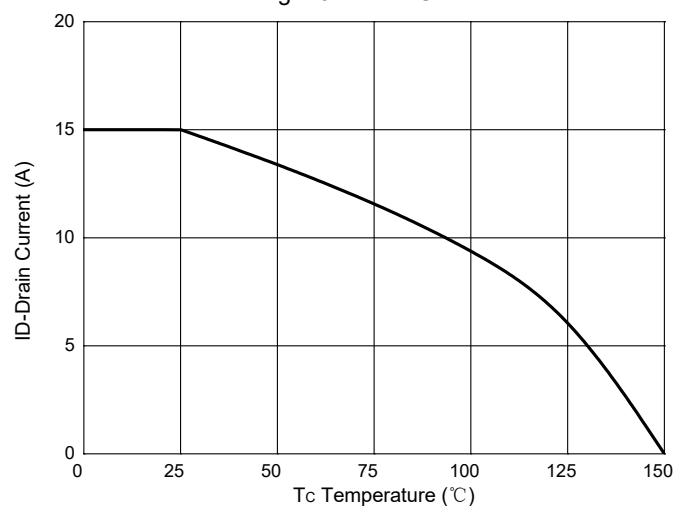
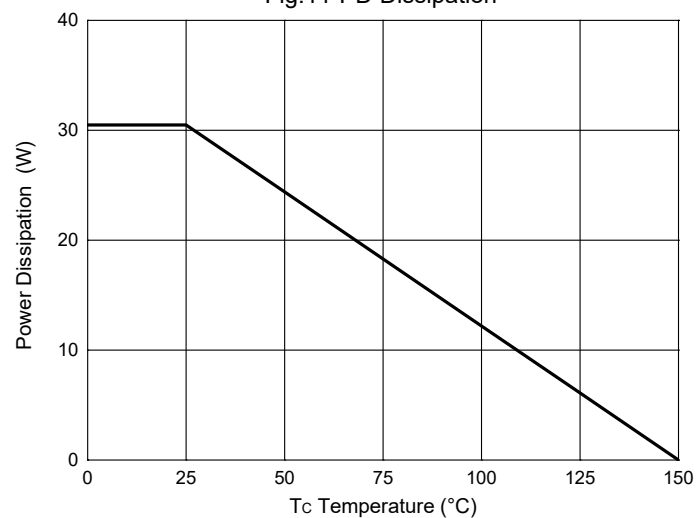


Fig.11-PD Dissipation



Curve Characteristics

Fig. 12 - Safe Operation Area

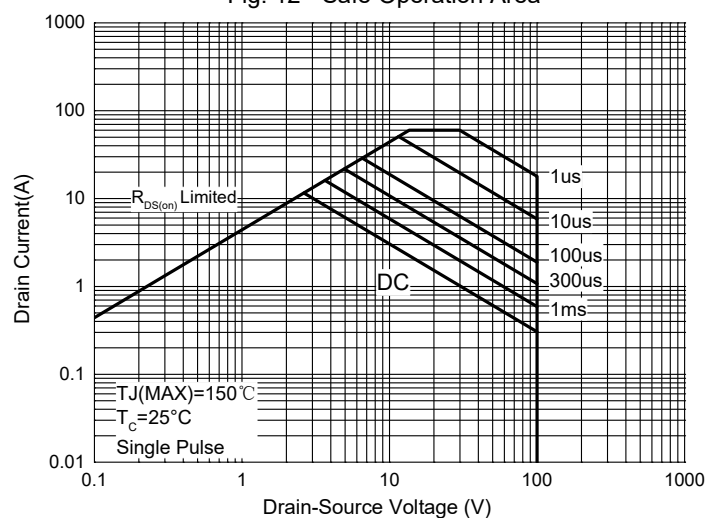
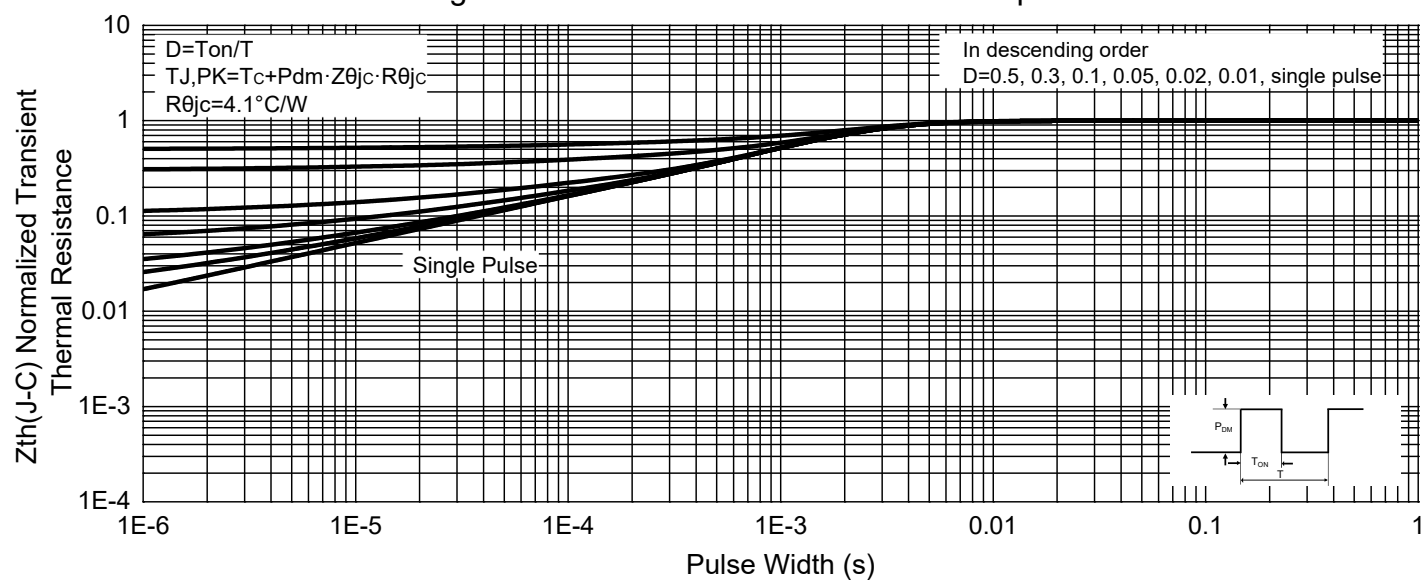


Fig. 13 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel: 5Kpcs/Reel

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